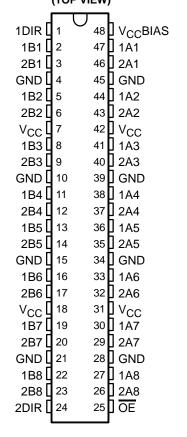
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- **Members of the Texas Instruments** Widebus™ Family
- Support the VME64 ETL Specification
- Reduced, TTL-Compatible, Input Threshold Range
- High-Drive Outputs ($I_{OH} = -60 \text{ mA}$, I_{OL} = 90 mA) Support 25- Ω Incident-Wave Switching
- **V_{CC}BIAS** Pin Minimizes Signal Distortion **During Live Insertion**
- Internal Pullup Resistor on OE Keeps **Outputs in High-Impedance State During Power Up or Power Down**
- Distributed V_{CC} and GND Pins Minimize **High-Speed Switching Noise**
- Equivalent 25- Ω Series Damping Resistor on B Port
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors

description

The 'ABTE16245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements. These devices can be used as two 8-bit transceivers or

SN54ABTE16245 . . . WD PACKAGE SN74ABTE16245 . . . DGG OR DL PACKAGE (TOP VIEW)



one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated. When \overline{OE} is low, the device is active.

The B port has an equivalent 25- Ω series output resistor to reduce ringing. Active bus-hold inputs also are on the B port to hold unused or floating inputs at a valid logic level.

The A port provides for the precharging of the outputs via V_{CC} BIAS, which establishes a voltage between 1.3 V and 1.7 V when V_{CC} is not connected.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments



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ORDERING INFORMATION

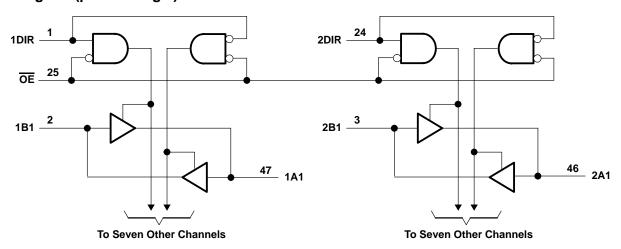
TA	PACK	∖GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DL	Tube	SN74ABTE16245DL	ABTE16245
–40°C to 85°C	330F - DL	Tape and reel	SN74ABTE16245DLR	ADTE 10245
	TSSOP – DGG	Tape and reel	SN74ABTE16245DGGR	ABTE16245
–55°C to 125°C	CFP – WD	Tube	SNJ54ABTE16245WD	SNJ54ABTE16245WD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each 8-bit section)

INP	UTS	ODED ATION					
OE	DIR	OPERATION					
L	L	A data to B bus					
L	Н	B data to A bus					
Н	X	Isolation					

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC} and V _{CC} BIAS	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, I _O	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	70°C/W
DL package	63°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The package thermal impedance is calculated in accordance with JESD 51-7.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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recommended operating conditions (see Note 3)

			SN54	ABTE16	6245	SN74	ABTE16	3245	UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII	
V _{CC} , V _{CC} BIAS	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
V	High-level input voltage	ŌĒ	2			2			V	
VIH	High-level input voltage	Except OE	1.6			1.6			V	
\/	Low lovel input voltage	ŌĒ			0.8			0.8	V	
VIL	Low-level input voltage	Except OE			1.4			1.4	V	
٧ _I	Input voltage		0		VCC	0		Vcc	V	
lou	High lovel output ourrent	B bus			-12			-12	mA	
ЮН	High-level output current	A bus			-24			-60	mA	
la.	Low lovel output oursest	B bus			12			12	A	
lOL	Low-level output current	A bus			64			90	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled			10			10	ns/V	
T _A	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAF	DAMETED	TEST 00	NDITIONS	SN	54ABTE1	6245	SN	74ABTE	16245	LIAUT
PAR	RAMETER	1551 CC	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
		V _{CC} = 5.5 V,	$C = 5.5 \text{ V}, \qquad I_{OH} = -100 \mu\text{A}$			V _{CC} -0.2			V _{CC} -0.2	
	B port	V 45V	I _{OH} = -1 mA	2.4			2.4			
V		V _{CC} = 4.5 V	I _{OH} = -12 mA	2			2			V
VOH		$V_{CC} = 5.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$			4.5			4.5	V
	A port	V 45V	I _{OH} = -32 mA	2.4			2.4			
		V _{CC} = 4.5 V	I _{OH} = -64 mA				2			
	D nort	V 45V	I _{OL} = 1 mA			0.4			0.4	
V	B port	V _{CC} = 4.5 V	I _{OL} = 12 mA						0.8	V
VOL	A port	V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55			0.55	V
	A port	vCC = 4.5 v	I _{OL} = 90 mA						0.9	
		V 45V	V _I = 0.8 V	100			100			
I _I (hold)	B port	V _{CC} = 4.5 V	V _I = 2 V	-100			-100			μΑ
		$V_{CC} = 5.5 \text{ V},$	V _I = 0 to 5.5 V			±500			±500	
1.	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1			±1	
tı	A or B ports	vCC = 5.5 v,	AL = ACC OLGIAD			±20			±20	μΑ
lozh [‡]	A port	$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			10			10	μΑ
lozL [‡]	A port	V _{CC} = 5.5 V,	V _O = 0.5 V			-10			-10	μΑ
1-	A port	V 55V	V- 25V	-50	-120	-180	-50		-180	mA
Ю	B port	V _{CC} = 5.5 V,	V _O = 2.5 V	-25	-52	-90	-25		-90	mA
l _{off}		$V_{CC} = 0$, V_{I} or $V_{O} \le$	4.5 V, V _{CC} BIAS = 0			±100			±100	μΑ
			Outputs high		28	36		28	36	
Icc	A or B ports	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		38	48		38	48	mA
		V1 = VCC 01 014B	Outputs disabled		20	32		20	32	
loop	A or B ports	V _{CC} = 5 V,	OE high		0.02			0.02		mA/
ICCD	A OI B POILS	C _L = 50 pF	OE low		0.33			0.33		MHz
C _i	Control inputs	V _I = 2.5 V or 0.5 V				10		2.5	4	pF
C _{io}	I/O ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$				13		4.5	8	pF

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

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live-insertion specifications over recommended operating free-air temperature range

DADA	METER		TEST CONDITIONS	SN54	ABTE16	6245	SN74	UNIT			
PARAI	VIETER		TEST CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
loo (Va	a PIAC)	$V_{CC} = 0 \text{ to } 4.5$ $I_{O(DC)} = 0$	V, V _{CC} BIAS = 4.5 V to 5.5		250	700		250	700		
ICC (VC	:Свіко)	$V_{CC} = 4.5 \text{ V to}$ $I_{O(DC)} = 0$	5.5 V [‡] , V _{CC} BIAS = 4.5 V t			20			20	μΑ	
Va	A nort	VCC = 0	V _{CC} BIAS = 4.5 V to 5.5 V	/	1.1	1.5	1.9	1.1	1.5	1.9	V
Vo	A port	AGC = 0	V _{CC} BIAS = 4.75 V to 5.2	1.3	1.5	1.7	1.3	1.5	1.7	V	
la	A nort	V22 - 0	VCCBIAS = 4.5 V	V _O = 0	-20		-100	-20		-100	μΑ
'0	IO A port $VCC = 0$,		V (ССЫАЗ = 4.5 V	V _O = 3 V	20		100	20		100	μΑ

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷ ₀ ۲٫	V _{CC} = 5 V, T _A = 25°C			SN54ABTE16245		SN74ABTE16245		
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN			
^t PLH	А	В	1.5	3.3	4.2	1.5	5.4	1.5	5.2	ns	
^t PHL	A	Ь	1.5	3.8	4.6	1.5	5.4	1.5	5.2	115	
^t PLH	В	۸	1.5	3	3.8	1.5	4.7	1.5	4.5	no	
^t PHL	Ь	A	1.5	3.1	4	1.5	4.7	1.5	4.5	ns	
^t PZH	ŌĒ	^	2	3.9	5.3	2	6.4	2	6.2	ns ns	
tpZL	OE .	Α	2	4.4	5.9	2	7	2	6.8		
^t PZH		В	2	4.5	6	2	7.3	2	7.1		
tPZL	ŌĒ	В	2	5	6.4	2	7.5	2	7.3		
^t PHZ	ŌĒ	Δ.	2	4.9	5.9	2	7	2	6.7		
^t PLZ] OE	Α	2	3.7	4.6	2	5.4	2	5.1	ns	
^t PHZ	ŌĒ	В	2	5.2	6.2	2	7.2	2	7	ns I	
^t PLZ]		2	4	5	2	5.8	2	5.5		



[‡] VCC - 0.5 V < VCCBIAS

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extended switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD	V(CC = 5 V 4 = 25°C	<u>',</u>	SN54ABT	E16245	SN74ABTI	E16245	UNIT
	(IIVI O1)	(0011 01)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	В	А	Rχ = 13 Ω	1.5	3.2	4	1.5	5	1.5	4.8	ns
t _{PHL}	ם	^	Λχ = 13 22	1.5	3.8	4.7	1.5	5.8	1.5	5.6	115
tPLH	В	А	Rχ = 26 Ω	1.5	3.1	4	1.5	4.8	1.5	4.6	ns
tPHL	ם	^	Λχ = 20 12	1.5	3.5	4.4	1.5	5.2	1.5	4.9	115
t _{PLH}	В	А	R _X = 56 Ω	1.5	3	3.8	1.5	4.7	1.5	4.5	ns
t _{PHL}	Б	A	$K\chi = 50.22$	1.5	3.3	4.2	1.5	5.1	1.5	4.7	115
	В	А	R _X = Open		0.1	0.6		2		2	
^t sk(p)	А	В	R _X = Open		0.4	0.8		2		2	ns
	В	А	$R_X = 26 \Omega$		0.3	8.0		2		2	
	В	А	R _X = Open		0.3	0.7		1.3		1.3	
tsk(o)	Α	В	R _X = Open		0.7	1.1		1.3		1.3	ns
	В	А	$R_X = 26 \Omega$		0.5	1		1.3		1.3	
tt†	В	А	$R_X = 26 \Omega$	0.5	0.8	1.5	0.5	1.5	0.5	1.5	ns
t _t ‡	Α	В	R _X = Open	3.5	5.5	7.3	3.5	8.1	3.5	7.9	ns

 $[\]dagger$ t_t is measured between 1 V and 2 V of the output waveform.

extended output characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (see Figures 1 and 2)

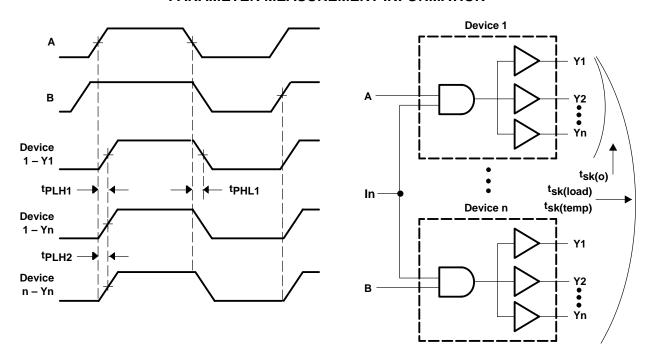
PARAMETER	FROM TO		TEST CONDITIONS	LOAD	SN54ABTE	16245	SN74ABTE	SN74ABTE16245	
PARAMETER	(INPUT)	(OUTPUT)	1E31 CONDITIONS	LOAD	MIN	MAX	MIN	MAX	UNIT
• • • •	Α	В	V _{CC} = constant,			3		2.5	
^t sk(temp)	В	Α	$\Delta T_A = 20^{\circ}C$	$R\chi = 56 \Omega$		4.5		4	ns
^t sk(load)	В	В	V _{CC} = constant, Temperature = constant	$R_X = 13, 26,$ or 56Ω		4.5		4	ns



[‡]t_t is measured between 10% and 90% of the output waveform.

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PARAMETER MEASUREMENT INFORMATION

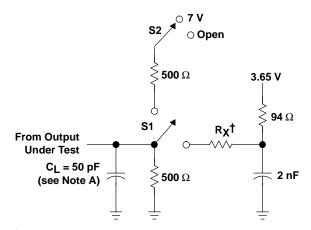


- NOTES: A. Pulse skew, $t_{sk(p)}$, is defined as the difference in propagation-delay times t_{PLH1} and t_{PHL1} on the same terminal at identical operating conditions.
 - B. Output skew, t_{Sk(0)}, is defined as the difference in propagation delay of any two outputs of the same device switching in the same direction (e.g., |t_{PLH1} t_{PLH2}|).
 - C. Temperature skew, $t_{sk(temp)}$, is the output skew of two devices, both having the same value of $V_{CC} \pm 1\%$ and with package temperature differences of 20°C.
 - D. Load skew, $t_{sk(load)}$, is measured with R_X in Figure 2 at 13 Ω for one unit and 56 Ω for the other unit.

Figure 1. Voltage Waveforms for Extended Characteristics

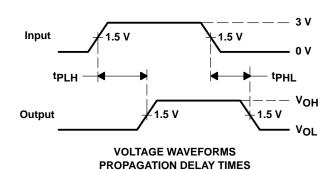
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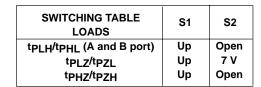
PARAMETER MEASUREMENT INFORMATION



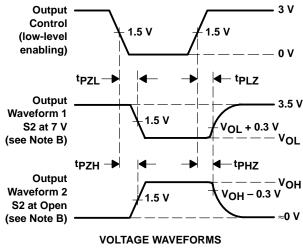
 $\dagger R_{X} = 13, 26, or 56 \Omega$

LOAD CIRCUIT FOR OUTPUTS





EXTENDED SWITCHING TABLE	S1	S2
LOADS	31	32
tpLH/tpHL/tsk (A port)	Down	Х
tpLH/tpHL/tsk (B port)	Up	Open
t _t (A port) (see Note E)	Down	Х
t _t (B port) (see Note F)	Up	Open



ENABLE AND DISABLE TIMES

- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_t is measured between 1 V and 2 V of the output waveform.
 - F. t_t is measured between 10% and 90% of the output waveform.

Figure 2. Load Circuit and Voltage Waveforms







25-Oct-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-9677501QXA	ACTIVE	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9677501QX A SNJ54ABTE16245 WD	Samples
SN74ABTE16245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16245	Samples
SN74ABTE16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16245	Samples
SN74ABTE16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16245	Samples
SN74ABTE16245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16245	Samples
SNJ54ABTE16245WD	ACTIVE	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9677501QX A SNJ54ABTE16245 WD	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sh/Rr): Til defines "Green" to mean Ph-Free (RoHS compatible) and free of Browing (Rr) and Antimony (Sh) based flame retardants (Br or Sh do not exceed 0.1% by w

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

25-Oct-2016

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ABTE16245, SN74ABTE16245:

Catalog: SN74ABTE16245

www.ti.com

Military: SN54ABTE16245

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTE16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ABTE16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

www.ti.com 26-Jan-2013



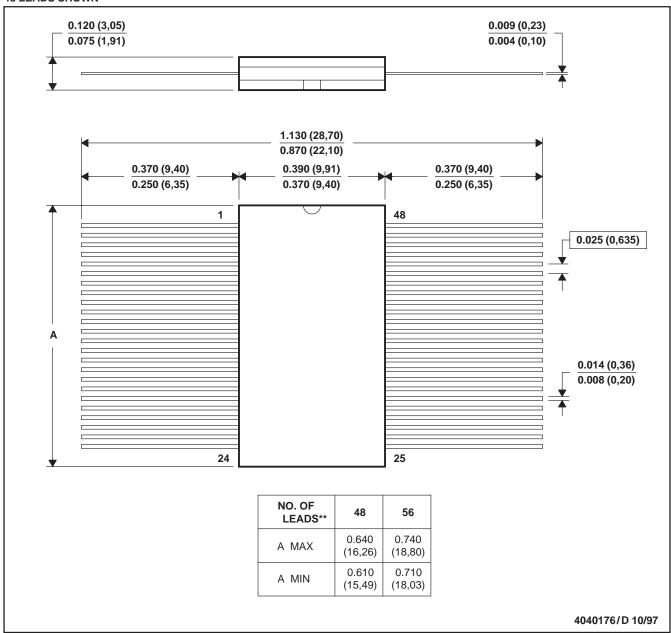
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ABTE16245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0	
SN74ABTE16245DLR	SSOP	DL	48	1000	367.0	367.0	55.0	

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



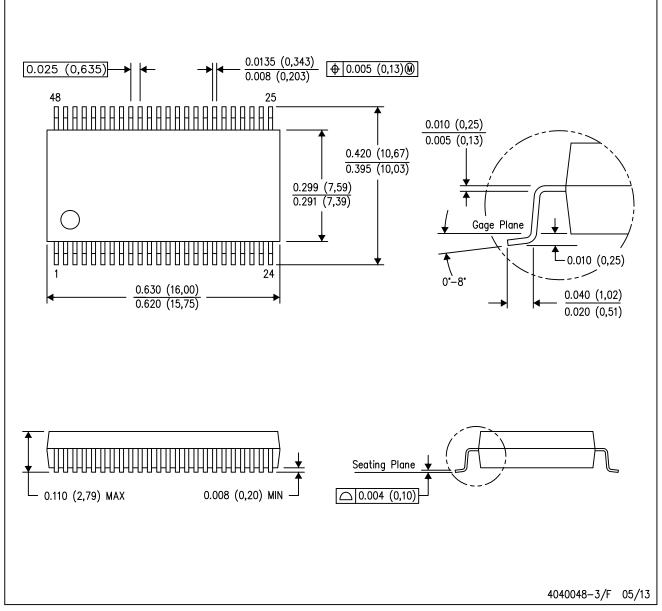
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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